

A Leading Manufacturer of High Reliability Printed Circuit Boards

Manufacturing Capabilities

ATTRIBUTES	STANDARD	ADVANCED	DEVELOPMENT (NPI Only)
Panel Size	12 x 18, 18 x 24, 21 x 24	20 x 26	21 x 27
Layer Counts	2 - 28	30 - 38	40 +
Flex Layer Counts	4 - 6	8 - 10	12 - 18
Rigid Flex Layer Counts	4 - 14	16 - 20	22 - 30
Cavity Sizes	1.0" x 1.0"	.750" x .750"	< .500" x .500"
LAMINATES - MATERIALS			
Pb Free RoHs - 180 Tg FR4	Yes	Yes	Yes
Med Loss - FR408 HR, -13EP	Yes	Yes	Yes
Low Loss - 13EPSI, I-Speed	Yes	Yes	Yes
Ultra Low Loss - Meg 6, I-Tera	Yes	Yes	Yes
Polyimide	Yes	Yes	Yes
Rogers Laminates	Yes	Yes	Yes
Flex - Dupont AP	Yes	Yes	Yes
Flex - Dupont LF	Yes	Yes	Yes
Flex - Dupont FR	Yes	Yes	Yes
Halogen Free	Yes	Yes	Yes
IMAGED TRACE / SPACE / PAD			
Internal Line Width	.003"	.002"	.0015"
Internal Spacing	.003"	.002"	.0015"
External Line Width	.003"	.002"	.0015"
External Spacing	.003"	.002"	.0015"
Minimum pad	.015"	.010"	.008"
Impedance Tolerance	10%	5%	<5%
SMT Pitch	.010"	.008"	.006"
VIA - PTH TOLERANCES			
Smallest Drilled Via	.0079"	.005"	.004"
Aspect Ratio	10:1	14:1	18:1
Minimum Cu Clearance to Hole	.008"	.006"	.004"
PTH Tolerance [+/-]	.003"	.002"	.0015"
NPTH Tolerance	.001"	.001"	.001"
Back Drill Depth Tolerance	.005"	.003"	.002"
HDI CAPABILITIES			
Sequential Lamination	3x Lam Cycles	5x Lam Cycles	7x Lam Cycles
Laser Micro Vias	.0045"	.003"	.003"
Blind Aspect Ratio	.75:1	1:1	1.2:1
Blind/Buried Vias	.004"	.003"	.003"
Via in Pad	Epoxy or Copper Filled	-	-
Laser Routing Board Thickness	<.040"	.040"-.062"	.062" +
SOLDER MASK-NOMENCLATURE			
Taiyo LPI	Green, Blue, Red	Black, White	All Colors
Minimum Clearance	.003"	.002"	.001"
Minimum Web	.004"	.003"	.002"
Legend Color	White	Black, Yellow, Orange	All Colors
TEST & MEASUREMENT			
Flying Probe Test	Yes	Yes	Yes
Fixture Test	Yes	Yes	Yes
TDR	Yes	Yes	Yes
Ionics	Yes	Yes	Yes
CMI XRF	Yes	Yes	Yes

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